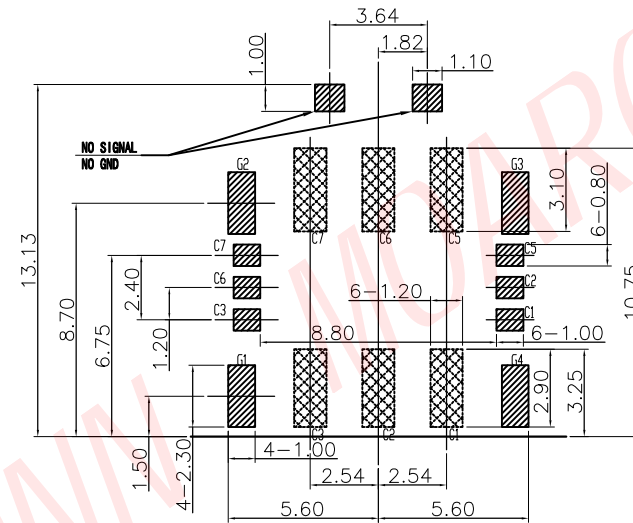
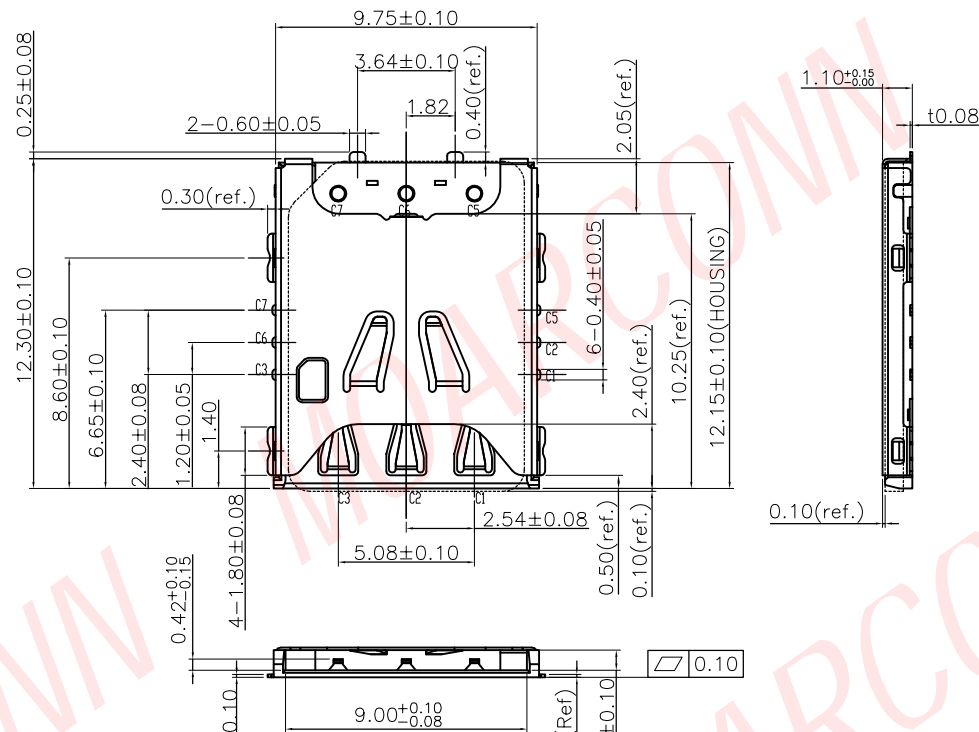


All materials, plating and process meet HF requirements.



(X1)
NANO SIM CARD PIN-MAP

C1	V _{cc} t
C2	RST
C3	CLT
C5	GND
C6	V _{pp}
C7	I/O

G1~G4	GND
-------	-----

Recommended PCB Layout
Top View (Tolerance ±0.05)



Pad Area



Via and Trace keepout Area

— PCB Edge

NOTE:

1. Material:

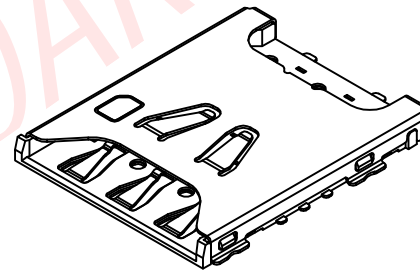
- 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
- 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
- 1-3 Cover: SUS304-H T=0.10±0.03mm

2. Plating:

- 2-1 Contact terminal:
Contact area: Gold 1u" Min.
Solder area: Gold 0.8u" Min.
Underplating: Ni overall 50u" Min.
- 2-2 Cover:
Underplating: Ni overall 50u" Min.
Solder area: Gold 0.8u" Min.

3. Specification:

- 3-1. Current Rating : 0.5mA AC/DC max.
- 3-2. Voltage Rating : 125V AC/DC
- 3-3. Ambient Temperature Range : -20°C~+60°C
- 3-4. Storage Temperature Range : -40°C~+70°C
- 3-5. Ambient Humidity Range : 95% R.H. Max.
- 3-6. Contact Resistance: 100m max.
- 3-7. Insulation Resistance: 1000M min./500VDC



X1	----	Add pin definition	Seven	2023.12.25
X0	----	NEW RELEASE	Aaron	2023.01.07
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : NANO SIM CARD CONN. PUSH-PULL TYPE HL. 10mm	DRAWING: Seven	DATE: 2023.12.25
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : NS110-T1151-01	CHECK: DATE:	DATE:		
	DRAWING NO. : D-NS110-T1151-01	APPROVED:	DATE:		
	SCALE: 1:1	DWG ID: C D	REV.: X1	PAGE: 1 OF 1	